

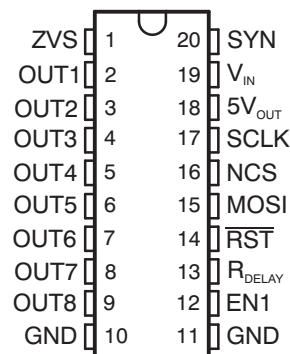
## FEATURES

- Eight Low-Side Drivers With Internal Clamp for Inductive Loads and Current Limiting for Self Protection
  - Seven Outputs Rated at 150 mA and Controlled Through Serial Interface
  - One Output Rated at 150 mA and Controlled Through Serial Interface and Dedicated Enable Pin
- 5-V  $\pm$  5% Regulated Power Supply With 200-mA Load Capability at  $V_{IN}$  Max of 18 V
- Internal Voltage Supervisory for Regulated Output
- Serial Communications for Control of Eight Low-Side Drivers
- Enable/Disable Input for OUT1
- 5-V or 3.3-V I/O Tolerant for Interface to Microcontroller
- Programmable Power-On Reset Delay Before  $\overline{RST}$  Asserted High, Once 5 V Is Within Specified Range (6 ms Typ)
- Programmable Deglitch Timer Before  $\overline{RST}$  Asserted Low (40  $\mu$ s Typ)
- Zero-Voltage Detection Signal
- Thermal Shutdown for Self Protection

## APPLICATIONS

- Electrical Appliances
  - Air Conditioning Units
  - Ranges
  - Dishwashers
  - Refrigerators
  - Microwaves
  - Washing Machines
- General-Purpose Interface Circuits, Allowing Microcontroller Interface to Relays, Electric Motors, LEDs, and Buzzers

N OR PWP PACKAGE  
(TOP VIEW)



## DESCRIPTION/ORDERING INFORMATION

The power supply provides regulated 5-V output to power the system microcontroller and drive eight low-side switches. The ac zero-detect circuitry is monitoring the crossover voltage of the mains ac supply. The resultant signal is a low-frequency clock output on the ZVS terminal, based on the ac-line cycle. This information allows the microcontroller to reduce in-rush current by powering loads on the ac-line peak voltage.

A serial communications interface controls the eight low-side outputs; each output has an internal snubber circuit to absorb the energy in the inductor at turn OFF. Alternatively, the system can use a fly-back diode to  $V_{IN}$  to help recirculate the energy in an inductive load at turn OFF.

### ORDERING INFORMATION<sup>(1)</sup>

$T_A$	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	PDIP – N	Tube of 20	TPIC9201N	TPIC9201N
	PowerPAD™ – PWP	Reel of 2000	TPIC9201PWPR	IC9201
		Tube of 70	TPIC9201PWP	

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

(2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).



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# TPIC9201 MICROCONTROLLER POWER SUPPLY AND MULTIPLE LOW-SIDE DRIVER

SLIS115D–APRIL 2005–REVISED FEBRUARY 2008

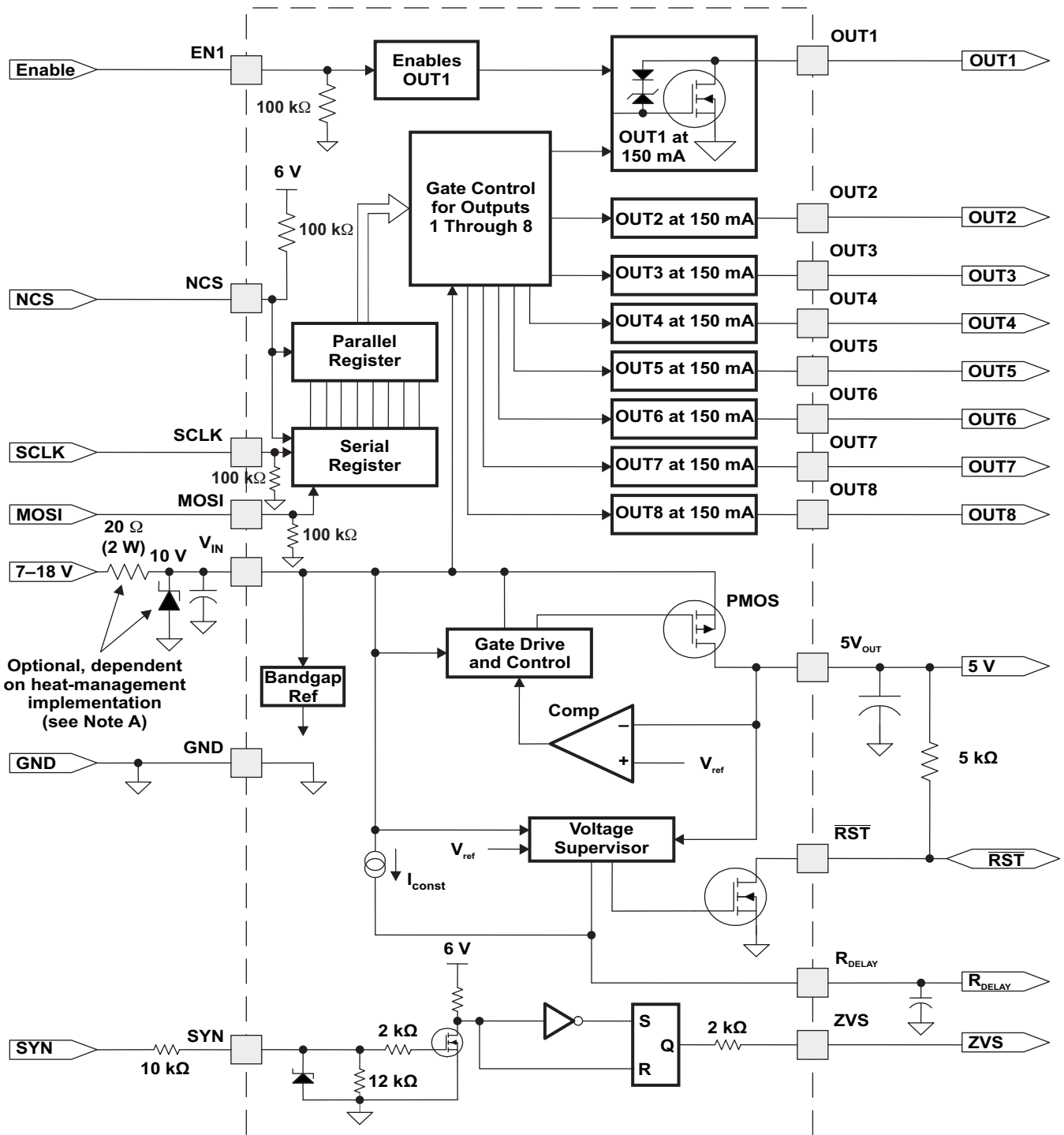
## PINOUT CONFIGURATION

NO.	NAME	I/O	DESCRIPTION
1	ZVS	O	Zero-voltage synchronization
2	OUT1	O	Low-side output 1
3	OUT2	O	Low-side output 2
4	OUT3	O	Low-side output 3
5	OUT4	O	Low-side output 4
6	OUT5	O	Low-side output 5
7	OUT6	O	Low-side output 6
8	OUT7	O	Low-side output 7
9	OUT8	O	Low-side output 8
10 <sup>(1)</sup>	GND	I	Ground
11 <sup>(1)</sup>	GND	I	Ground
12	EN1	I	Enable/disable for OUT1
13	R <sub>DELAY</sub>	O	Power-up reset delay
14 <sup>(2)</sup>	$\overline{\text{RST}}$	I/O	Power-on reset output (open drain, active low)
15	MOSI	I	Serial data input
16	NCS	I	Chip select
17	SCLK	I	Serial clock for data synchronization
18	5V <sub>OUT</sub>	O	Regulated output
19	V <sub>IN</sub>	I	Unregulated input voltage source
20	SYN	I	AC zero detect input

(1) Terminals 10 and 11 are fused internally in the lead frame for the 20-pin PDIP package.

(2) Terminal 14 can be used as an input or an output.

**FUNCTIONAL BLOCK DIAGRAM**



A. The resistor and Zener diode are required if there is insufficient thermal-management allocation.

# TPIC9201

## MICROCONTROLLER POWER SUPPLY AND MULTIPLE LOW-SIDE DRIVER

SLIS115D–APRIL 2005–REVISED FEBRUARY 2008

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### DETAILED DESCRIPTION

The 5-V regulator is powered from  $V_{IN}$ , and the regulated output is within  $5\text{ V} \pm 5\%$  over the operating conditions. The open-drain power-on reset ( $\overline{RST}$ ) pin remains low until the regulator exceeds the set threshold, and the timer value set by the capacitor on the reset delay ( $R_{DELAY}$ ) pin expires. If both of these conditions are satisfied,  $\overline{RST}$  is asserted high. This signifies to the microcontroller that serial communications can be initiated to the TPIC9201.

The serial communications is an 8-bit format, with data transfer synchronized using a serial clock from the microcontroller. A single register controls all the outputs (one bit per output). The default value is zero (OFF). If an output requires pulse width modulation (PWM) function, the register must be updated at a rate faster than the desired PWM frequency. OUT1 can be controlled by serial input from the microcontroller or with the dedicated enable (EN1) pin. If EN1 is pulled low or left open, the serial input through the shift register controls OUT1. If EN1 is pulled high, OUT1 always is turned on, and the serial input for OUT1 is ignored.

The SYN input translates the image of the mains voltage through the secondary of the transformer. The SYN input has a resistor to protect from high currents into the IC. The zero-voltage synchronization output translates the ac-line cycle frequency into a low-frequency clock, which can be used for a timing reference and to help power loads on the ac-line peak voltage (to reduce in-rush currents).

If  $\overline{RST}$  is asserted, all outputs are turned OFF internally, and the input register is reset to all zeroes. The microcontroller must write to the register to turn the outputs ON again.

**Absolute Maximum Ratings<sup>(1)</sup>**

			MIN	MAX	UNIT
V <sub>I(unreg)</sub>	Unregulated input voltage <sup>(2)</sup> <sup>(3)</sup>	V <sub>IN</sub>		24	V
		SYN		24	
V <sub>I(logic)</sub>	Logic input voltage <sup>(2)</sup> <sup>(3)</sup>	EN1, MOSI, SCLK, and NCS		7	V
		$\overline{\text{RST}}$ and R <sub>DELAY</sub>		7	
V <sub>O</sub>	Low-side output voltage	OUT1–OUT8		16.5	V
I <sub>LIMIT</sub>	Output current limit <sup>(4)</sup>	OUTn = ON and shorted to V <sub>IN</sub> with low impedance		350	mA
$\theta_{JA}$	Thermal impedance, junction to ambient <sup>(5)</sup>	N package		69	°C/W
		PWP package		33	
$\theta_{JC}$	Thermal impedance, junction to case <sup>(5)</sup>	N package		54	°C/W
		PWP package		20	
$\theta_{JP}$	Thermal impedance, junction to thermal pad <sup>(5)</sup>	PWP package		1.4	°C/W
P <sub>D</sub>	Continuous power dissipation <sup>(6)</sup>	N package		1.8	W
		PWP package		3.7	
ESD	Electrostatic discharge <sup>(7)</sup>			2	kV
T <sub>A</sub>	Operating ambient temperature range		–40	125	°C
T <sub>stg</sub>	Storage temperature range		–65	125	°C
T <sub>lead</sub>	Lead temperature	Soldering, 10 s		260	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to GND.
- (3) Absolute negative voltage on these pins must not go below –0.5 V.
- (4) Not more than one output should be shorted at a time, and duration of the short circuit should not exceed 1 ms.
- (5) The thermal data is based on using 1-oz copper trace with JEDEC 51-5 test board for PWP and JEDEC 51-7 test board for N.
- (6) The data is based on ambient temperature of 25°C max.
- (7) The Human-Body Model is a 100-pF capacitor discharged through a 1.5-k $\Omega$  resistor into each pin.

**Dissipation Ratings**

PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 125°C POWER RATING
N	1812 mW	14.5 mW/°C	362 mW
PWP	3787 mW	30.3 mW/°C	757 mW

**Recommended Operating Conditions**

			MIN	MAX	UNIT
V <sub>I(unreg)</sub>	Unregulated input voltage	V <sub>IN</sub>	7	18	V
		SYN	0	18	
V <sub>I(logic)</sub>	Logic input voltage	EN1, MOSI, SCLK, NCS, $\overline{\text{RST}}$ , and R <sub>DELAY</sub>	0	5.25	V
T <sub>A</sub>	Operating ambient temperature		–40	125	°C

# TPIC9201 MICROCONTROLLER POWER SUPPLY AND MULTIPLE LOW-SIDE DRIVER

SLIS115D–APRIL 2005–REVISED FEBRUARY 2008

## Electrical Characteristics

$T_A = -40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ ,  $V_{IN} = 7\text{ V}$  to  $18\text{ V}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
<b>Supply Voltage and Current</b>						
$V_{IN}^{(2)}$	Input voltage		7		18	V
$I_{VIN}$	Input supply current	Enable = ON, OUT1–OUT8 = Off			3	mA
		Enable = ON, OUT1–OUT8 = On			5	
<b>Logic Inputs (MOSI, NCS, SCLK, and EN1)</b>						
$V_{IL}$	Logic input low level	$I_{IL} = 100\ \mu\text{A}$			0.8	V
$V_{IH}$	Logic input high level	$I_{IL} = 100\ \mu\text{A}$	2.4			
<b>Reset (RST)</b>						
$V_{OL}$	Low-level logic output	$I_{OL} = 1.6\ \text{mA}$			0.4	V
$V_{OH}^{(3)}$	High-level logic output	5-k $\Omega$ pullup to $V_{CC}$	$V_{CC} - 0.8$			V
$V_H$	Disabling reset threshold	5-V regulator ramps up		4.25	4.5	V
$V_L$	Enabling reset threshold	5-V regulator ramps down		3.3	3.75	V
$V_{HYS}$	Threshold hysteresis		0.12	0.5		V
<b>Reset Delay (<math>R_{DELAY}</math>)</b>						
$I_{OUT}$	Output current		18	28	48	$\mu\text{A}$
$T_{DW}$	Reset delay timer	$C = 47\ \text{nF}$	3	6		ms
$T_{UP}$	Reset capacitor to low level	$C = 47\ \text{nF}$		45		$\mu\text{s}$
<b>Output (OUT1–OUT8)</b>						
$V_{OL}$	Output ON	$I_{OUTn} = 150\ \text{mA}$		0.4	0.7	V
$I_{OH}$	Output leakage	$V_{OH} = \text{Max of } 16.5\ \text{V}$			2	$\mu\text{A}$
<b>Regulator Output (<math>5V_{OUT}</math>)</b>						
$5V_{OUT}$	Output supply	$I_{5V_{OUT}} = 5\ \text{mA}$ to $200\ \text{mA}$ , $V_{IN} = 7\ \text{V}$ to $18\ \text{V}$ , $C_{5V_{OUT}} = 1\ \mu\text{F}$	4.75	5	5.25	V
$I_{5V_{OUT}} \text{ limit}$	Output short-circuit current	$5V_{OUT} = 0\ \text{V}$	200			mA
<b>Thermal Shutdown</b>						
$T_{SD}$	Thermal shutdown			150		$^{\circ}\text{C}$
$T_{HYS}$	Hysteresis			20		$^{\circ}\text{C}$
<b>Zero Voltage Synchronization (ZVS)</b>						
$V_{SYNTH}$	Transition threshold		0.4	0.75	1.1	V
$I_{SYN}$	Input activating current	$R_{ZV} = 10\ \text{k}\Omega$ , $V_{SYN} = 24\ \text{V}$			2	mA
$t_D$	Transition time	Rising and falling	10			$\mu\text{s}$

(1) All typical values are at  $T_A = 25^{\circ}\text{C}$ .

(2) There are external high-frequency noise-suppression capacitors and filter capacitors on  $V_{IN}$ .

(3)  $V_{CC}$  is the pullup resistor voltage.

## Output Control Register

MSB						LSB	
IN8	IN7	IN6	IN5	IN4	IN3	IN2	IN1
0	0	0	0	0	0	0	0

INn = 0: Output OFF

INn = 1: Output ON

To operate the output in PWM mode, the output control register must be updated at a rate twice the desired PWM frequency of the output. Maximum PWM frequency is 5 kHz. The register is updated every 100  $\mu$ s.

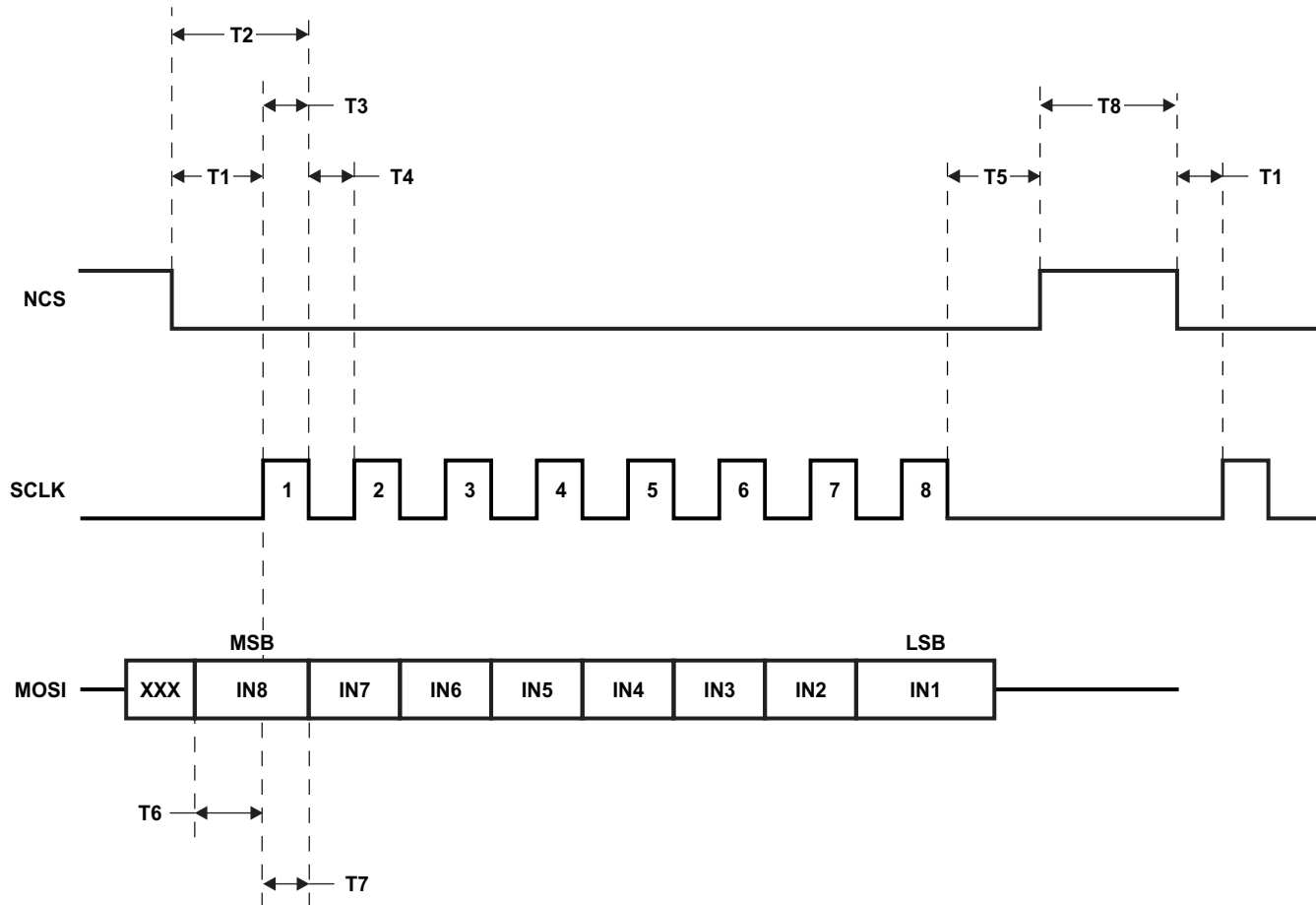
### ENABLE TRUTH TABLE

EN1	SERIAL INPUT FOR OUT1	OUT1
Open	H	On
Open	L	Off
L	H	On
L	L	Off
H	H	On
H	L	On

**Serial Communications Interface**

The serial communications is an 8-bit format, with data transfer synchronized using a serial clock from the microcontroller (see [Figure 1](#)). A single register controls all the outputs. The signal gives the instruction to control the output of TPIC9201.

The NCS signal enables the SCLK and MOSI data when it is low. After NCS is set low for  $T_1$ , synchronization clock and data begin to transmit and, after the 8-bit data has been transmitted, NCS is set high again to disable SCLK and MOSI and transfer the serial data to the control register. SCLK must be held low when NCS is in the high state.



**Figure 1. Serial Communications**

## Timing Requirements

$T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ ,  $V_{IN} = 7\text{ V}$  to  $18\text{ V}$  (unless otherwise noted)

		MIN	TYP	MAX	UNIT
$f_{SPI}$	SPI frequency		4		MHz
T1	Delay time, NCS falling edge to SCLK rising edge	10			ns
T2	Delay time, NCS falling edge to SCLK falling edge	80			ns
T3	Pulse duration, SCLK high	60			ns
T4	Pulse duration, SCLK low	60			ns
T5	Delay time, last SCLK falling edge to NCS rising edge	80			ns
T6	Setup time, MOSI valid before SCLK edge	10			ns
T7	Hold time, MOSI valid after SCLK edge	10			ns
T8	Time between two words for transmitting	170			ns

## Reset Delay ( $R_{DELAY}$ )

The  $R_{DELAY}$  output provides a constant current source to charge an external capacitor to approximately 6.5 V. The external capacitor is selected to provide a delay time, based on the current equation for a capacitor,  $I = C(\Delta v/\Delta t)$  and a 28- $\mu\text{A}$  typical output current.

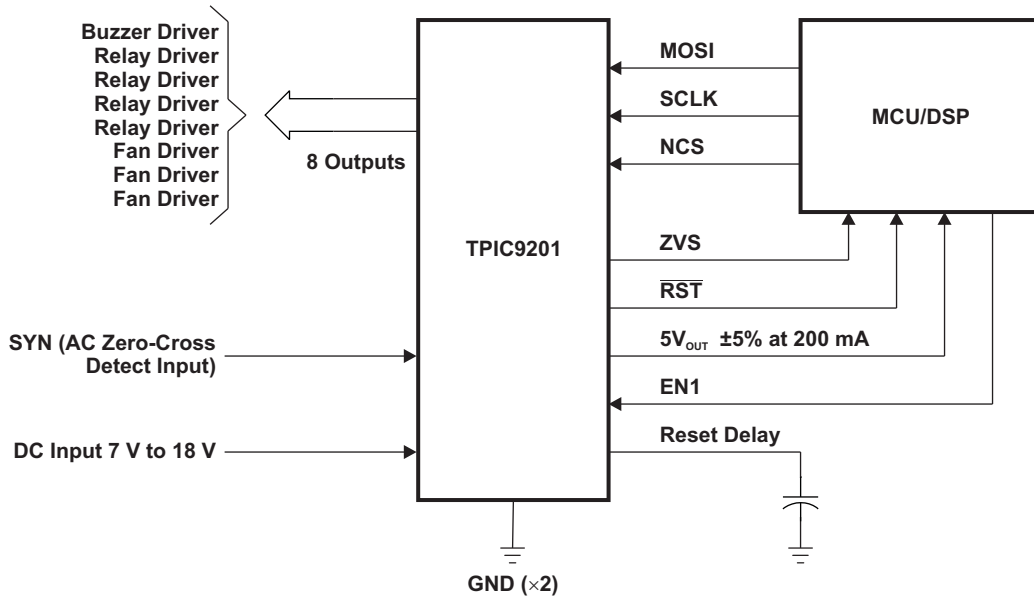
Therefore, the user should select a 47-nF capacitor to provide a 6-ms delay at 3.55 V.

$$I = C(\Delta v/\Delta t)$$

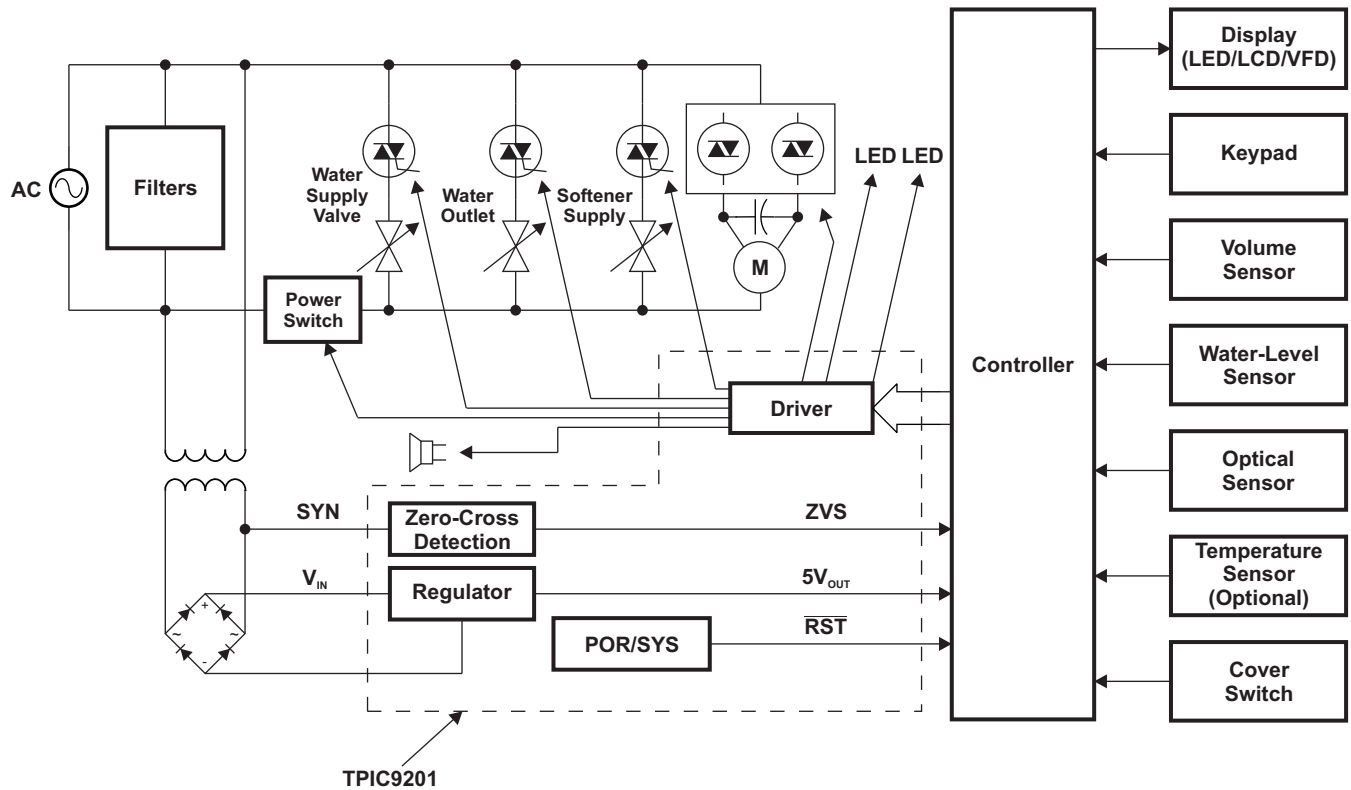
$$28\ \mu\text{A} = C \times (3.55\ \text{V}/6\ \text{ms})$$

$$C = 47\ \text{nF}$$

**APPLICATION INFORMATION**



**Figure 2. Typical Application**



**Figure 3. Washing-Machine Application**

## PCB Layout

To maximize the efficiency of this package for application on a single-layer or multilayer PCB, certain guidelines must be followed when laying out this part on the PCB.

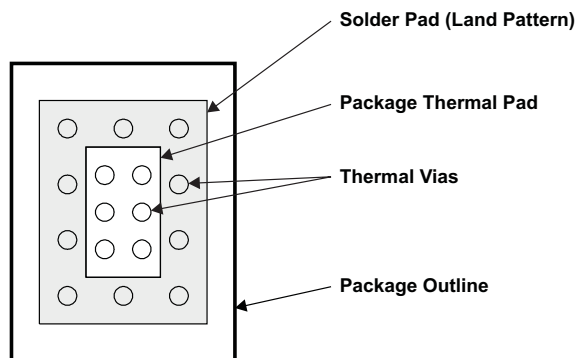
The following information is to be used as a guideline only.

For further information, see the PowerPAD concept implementation document.

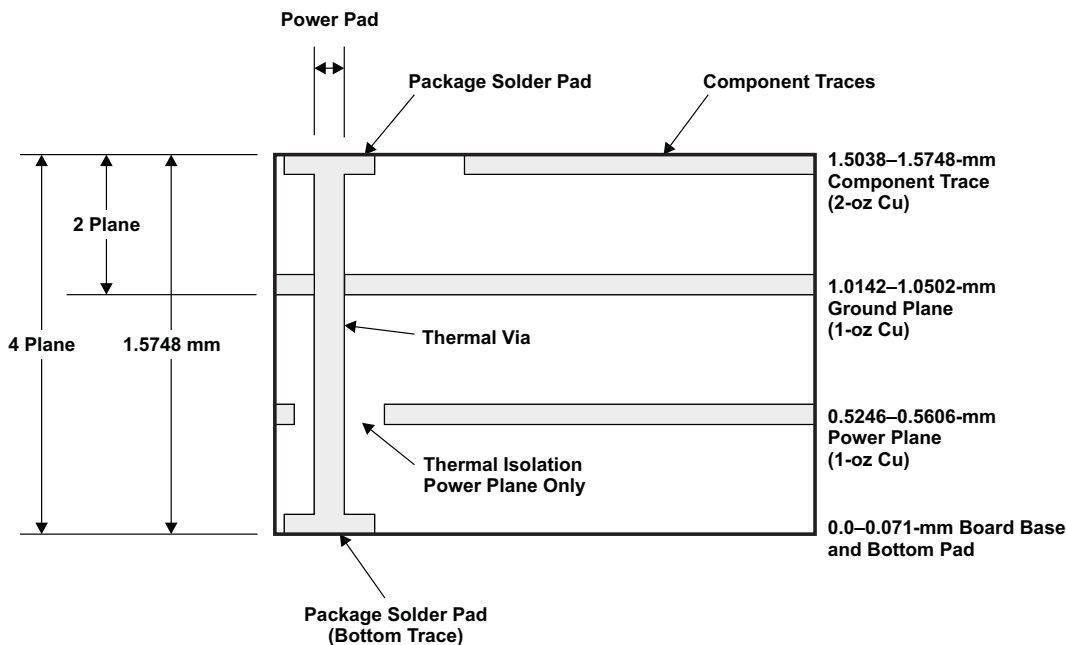
### Application Using a Multilayer PCB

In a multilayer board application, the thermal vias are the primary method of heat transfer from the package thermal pad to the internal ground plane (see [Figure 4](#) and [Figure 5](#)).

The efficiency of this method depends on several factors: die area, number of thermal vias, thickness of copper, etc. (see the *PowerPAD™ Thermally Enhanced Package Technical Brief*, literature number [SLMA002](#)).



**Figure 4. Package and PCB Land Configuration for a Multilayer PCB**



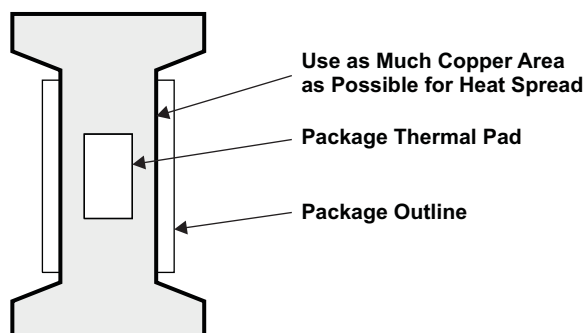
**Figure 5. Multilayer Board (Side View)**

### Application Using a Single-Layer PCB

In a single-layer board application, the thermal pad is attached to a heat spreader (copper area) by using the low thermal-impedance attachment method (solder paste or thermal-conductive epoxy). With either method, it is advisable to use as much copper trace area as possible to dissipate the heat.

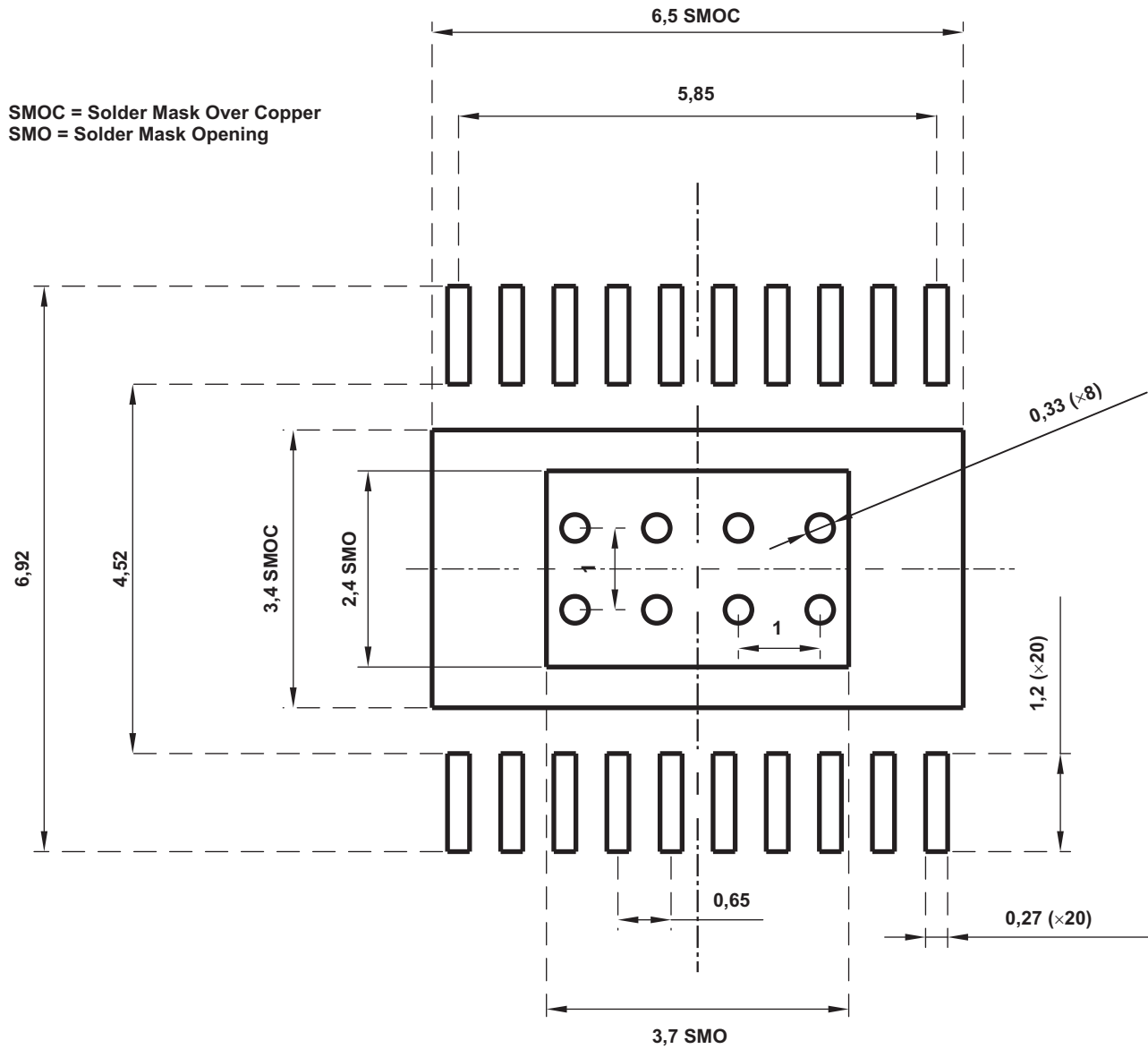
**CAUTION:**

If the attachment method is not implemented correctly, the functionality of the product cannot be ensured. Power-dissipation capability is adversely affected if the device is incorrectly mounted onto the circuit board.



**Figure 6. Layout Recommendations for a Single-Layer PCB**

**Recommended Board Layout**



**Figure 7. Recommended Board Layout for PWP**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPIC9201N	NRND	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPIC9201N	
TPIC9201PWP	NRND	HTSSOP	PWP	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	IC9201	
TPIC9201PWPR	NRND	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	IC9201	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

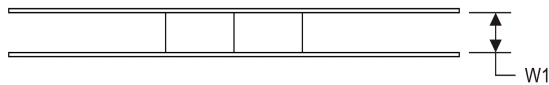
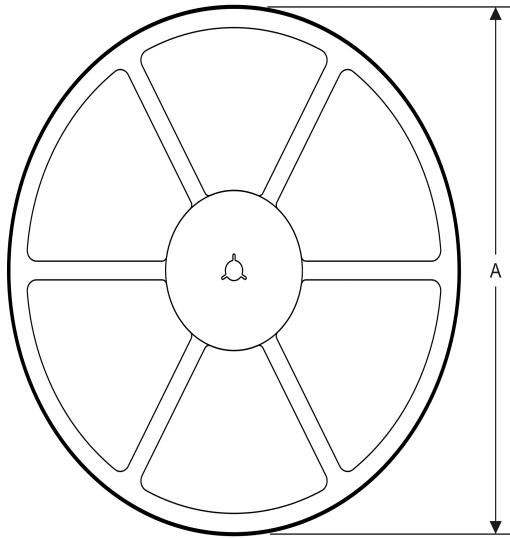
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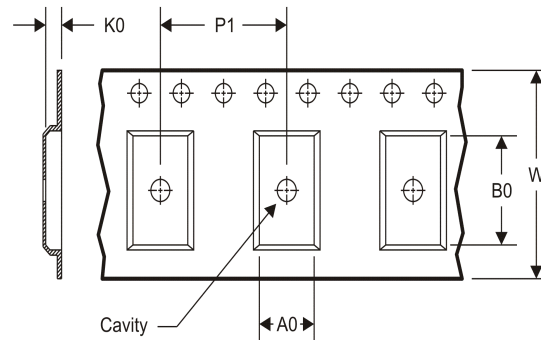
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**TAPE AND REEL INFORMATION**

**REEL DIMENSIONS**



**TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPIC9201PWPR	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



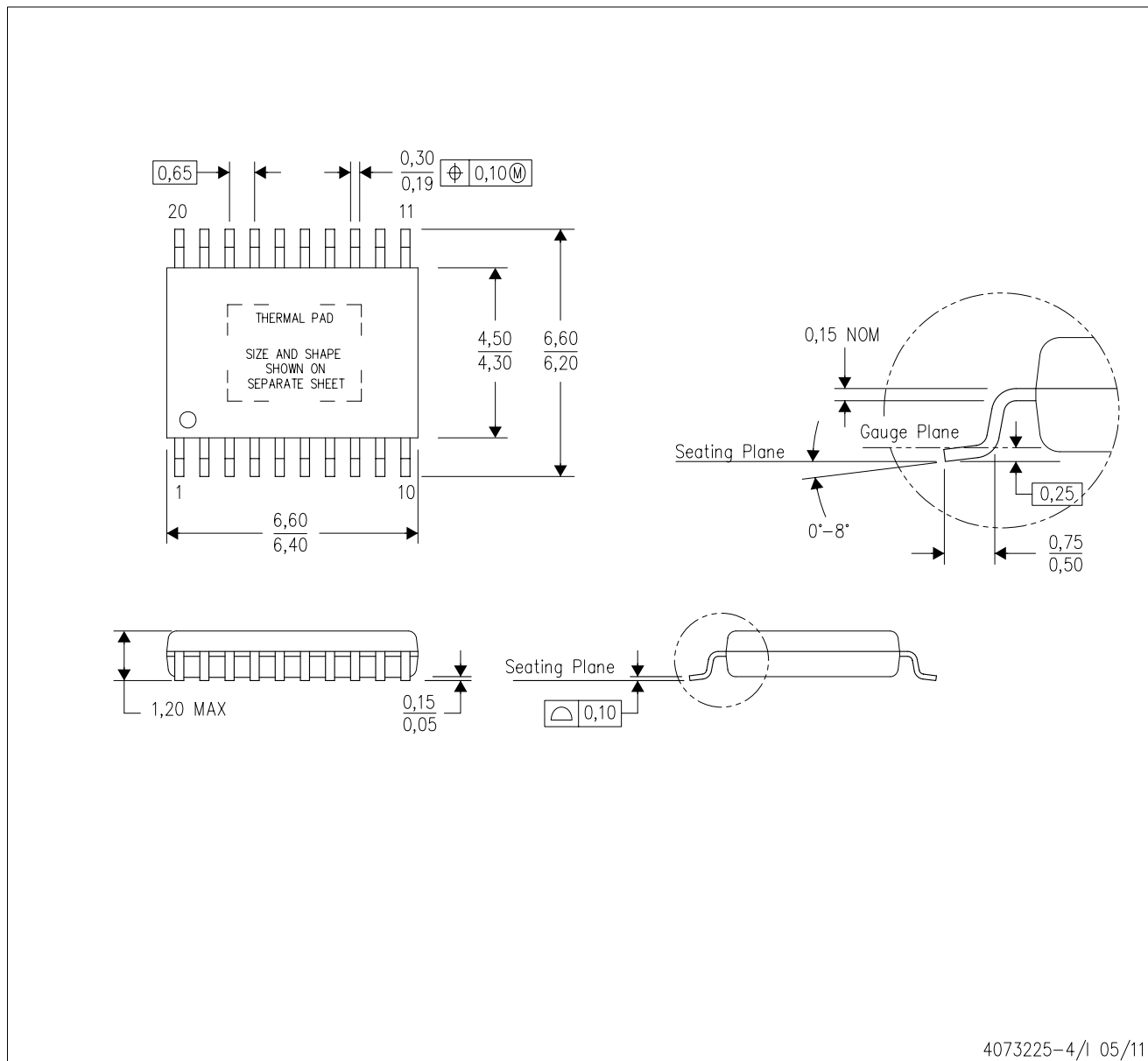
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPIC9201PWPR	HTSSOP	PWP	20	2000	367.0	367.0	38.0

# MECHANICAL DATA

PWP (R-PDSO-G20)

PowerPAD™ PLASTIC SMALL OUTLINE



4073225-4/1 05/11

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
  - Falls within JEDEC MO-153

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## THERMAL PAD MECHANICAL DATA

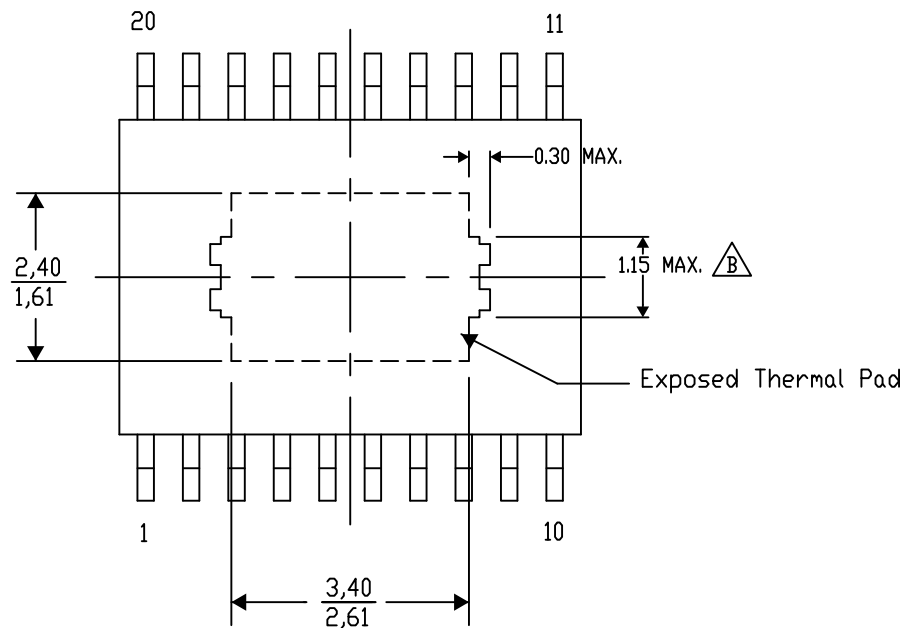
### PWP (R-PDSO-G20) PowerPAD™ SMALL PLASTIC OUTLINE

#### THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

Exposed Thermal Pad Dimensions

4206332-15/AH 11/13

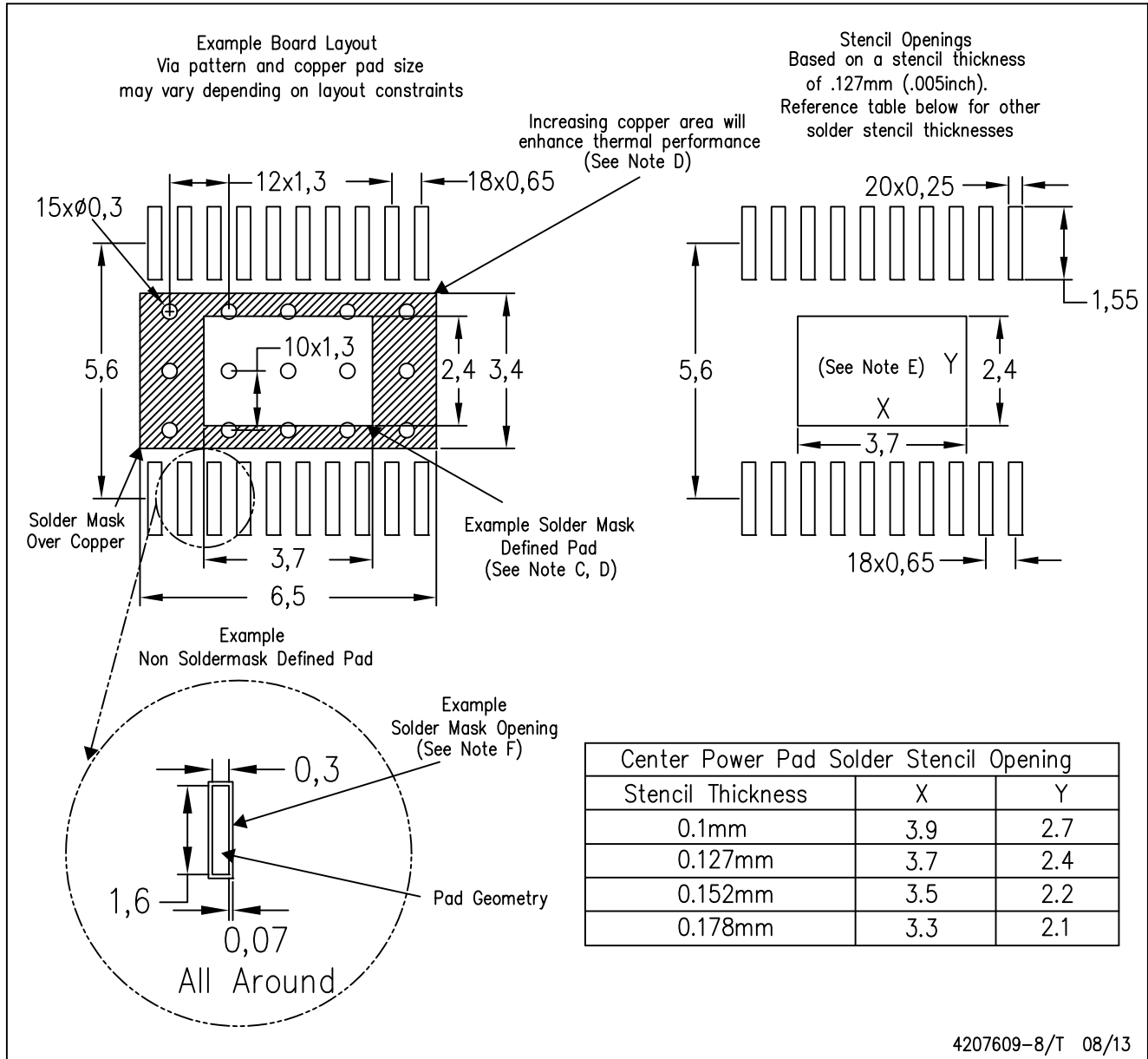
NOTE: A. All linear dimensions are in millimeters

 Exposed tie strap features may not be present.

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PWP (R-PDSO-G20)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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